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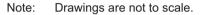
## 1. Pin Configurations and Pinouts

**Pin Configurations** 

Figure 1.

Pin Name	Function
SDA	Serial Data
SCL	Serial Clock Input
WP	Write Protect
A <sub>0</sub> to A <sub>2</sub>	Address Inputs
GND	Ground
V <sub>CC</sub>	Power Supply

8-lead SOIC	8-lead TSSOP
(Top View)	(Top View)
$A_0$ 18 $V_{CC}$ $A_1$ 27 $WP$ $A_2$ 36 $SCL$ $GND$ 45 $SDA$	A0 10 8 V <sub>CC</sub> A1 2 7 WP A2 3 6 SCL GND 4 5 SDA
8-pad l	JDFN
(Top V	/iew)
A0 A1 2 A2 3 GND 4	(8) V <sub>CC</sub> (7) WP (6) SCL (5) SDA



## 2. Absolute Maximum Ratings\*

Operating Temperature55°C to +125°C
Storage Temperature65°C to +150°C
Voltage on any pin with respect to ground1.0V to +7.0V
Maximum Operating Voltage
DC Output Current

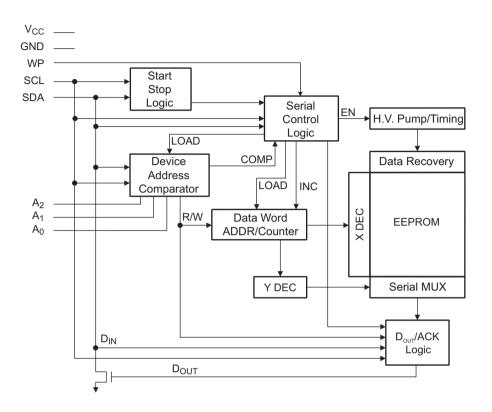
\*Notice: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



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# 3. Block Diagram







#### **Pin Description** 4.

Serial Clock (SCL): The SCL input is used to positive edge clock data into each EEPROM device and negative edge clock data out of each device.

Serial Data (SDA): The SDA pin is bidirectional for serial data transfer. This pin is open-drain driven and may be wire-ORed with any number of other open-drain or open-collector devices.

Device Addresses (A<sub>2</sub>, A<sub>1</sub>, A<sub>0</sub>): The A<sub>2</sub>, A<sub>1</sub>, and A<sub>0</sub> pins are device address inputs that are hardwired or left not connected for hardware compatibility with other Atmel AT24C devices. When the pins are hardwired, as many as eight 128K/256K devices may be addressed on a single bus system (device addressing is discussed in detail in Section 7., Device Addressing). If the pins are left floating, the  $A_2$ ,  $A_1$ , and  $A_0$  pins will be internally pulled down to GND if the capacitive coupling to the circuit board  $V_{CC}$  plane is < 3pF. If coupling is > 3pF, Atmel recommends connecting the pin to GND.

Write Protect (WP): AT24C128C/256C has a Write Protect pin that provides hardware data protection. The Write Protect pin allows normal read/write operations when connected to ground (GND). When the Write Protect pin is connected to V<sub>CC</sub>, the write protection feature is enabled and operates as shown in the following table.

tected

Normal Read/Write Operations

WP Pin Status	Part of the Array Protecte
At V <sub>CC</sub>	Full (128K/256K) Array

#### Table 4-1. Write Protect

At GND



### 5. Memory Organization

AT24C128C/256C, 128K/256KSerial EEPROM: The 128K/256K is internally organized as 256/512 pages of 64 bytes each. Random word addressing requires a 14/15 bit data Word Address.

### 5.1 Pin Capacitance

#### Table 5-1.Pin Capacitance<sup>(1)</sup>

Symbol	Test Condition	Max	Units	Conditions
C <sub>I/O</sub>	Input/Output Capacitance (SDA)	8	pF	V <sub>I/O</sub> = 0V
C <sub>IN</sub>	Input Capacitance (SCL)	6	pF	$V_{IN} = 0V$

Note: 1. This parameter is characterized and is not 100% tested.

### 5.2 DC Characteristics

#### Table 5-2. DC Characteristics

Applicable over recommended operating range from:  $T_{A1} = -40^{\circ}C$  to  $+125^{\circ}C$ ,  $V_{CC1} = 2.5V$  to 5.5V;  $T_{A2} = -40^{\circ}C$  to  $105^{\circ}C$ ,  $V_{CC2} = 1.7V$  to 5.5V. (unless otherwise noted).

Symbol	Parameter	Test Condition		Min	Тур	Max	Units
V <sub>CC1</sub>	Supply Voltage	Grade 1	Grade 1			5.5	V
V <sub>CC2</sub>	Supply vollage	Grade 2 <sup>(2)</sup> and 3		1.7		5.5	V
	Supply Current	$\gamma = E O \gamma$	Read at 100kHz		0.4	1.0	~
I <sub>CC</sub>	Supply Current	V <sub>CC</sub> = 5.0V	Write at 100kHz		2.0	3.0	mA
I <sub>SB1</sub>		V <sub>CC</sub> = 1.7V			0.1	3.0	
I <sub>SB2</sub>	Standby Current	V <sub>CC</sub> = 2.5V	$V_{IN}$ = $V_{CC}$ or $V_{SS}$	1.6	1.6	4.0	μA
I <sub>SB3</sub>		V <sub>CC</sub> = 5.0V	V <sub>CC</sub> = 5.0V		4.0	6.0	
ILI	Input Leakage Current	$V_{IN} = V_{CC} \text{ or } V_{SS}$			0.10	3.0	
I <sub>LO</sub>	Output Leakage Current	$V_{OUT} = V_{CC} \text{ or } V_{S}$	S		0.05	3.0	μA
V <sub>IL</sub>	Input Low Level <sup>(1)</sup>			-0.6		V <sub>CC</sub> x 0.3	V
V <sub>IH</sub>	Input High Level <sup>(1)</sup>			V <sub>CC</sub> x 0.7		V <sub>CC</sub> + 0.5	V
V <sub>OL1</sub>	Output Low-voltage	V <sub>CC</sub> = 2.5V	I <sub>OL</sub> = 3.00mA			0.4	V
V <sub>OH1</sub>	Output High-voltage	v <sub>CC</sub> = 2.5v	I <sub>OH</sub> = -1.60mA	$V_{CC} - 0.8$			V
V <sub>OL2</sub>	Output Low-voltage	V <sub>CC</sub> = 1.7V	I <sub>OL</sub> = 0.15mA			0.2	V
V <sub>OH2</sub>	Output High-voltage	v <sub>CC</sub> - 1.7 v	I <sub>OH</sub> = -100μA	$V_{CC} - 0.2$			V

Notes: 1.  $V_{IL}$  min and  $V_{IH}$  max are reference only and are not tested.

2. Contact Sales for Grade 2 Availability



6

### 5.3 AC Characteristics

### Table 5-3. AC Characteristics

Applicable over recommended operating range from  $T_A = -40^{\circ}$ C to  $+125^{\circ}$ C,  $V_{CC} = +1.7$ V to +5.5V, CL = 1 TTL Gate and 100pF unless otherwise noted or restricted by grade. Test conditions are listed in Note 3.

Symbol	Parameter	Min	Max	Units
f <sub>SCL</sub>	Clock Frequency, SCL		400	kHz
t <sub>LOW</sub>	Clock Pulse Width Low	1.2		μs
t <sub>HIGH</sub>	Clock Pulse Width High	0.6		μs
ti	Noise Suppression Time <sup>(1)</sup>		50	ns
t <sub>AA</sub>	Clock Low to Data Out Valid	0.1	0.9	μs
t <sub>BUF</sub>	Time the bus must be free before a new transmission can $\ensuremath{start}^{(2)}$	1.2		μs
t <sub>HD.STA</sub>	Start Hold Time	0.6		μs
t <sub>SU.STA</sub>	Start Set-up Time	0.6		μs
t <sub>HD.DAT</sub>	Data In Hold Time	0		μs
t <sub>SU.DAT</sub>	Data In Set-up Time	100		ns
t <sub>R</sub>	Inputs Rise Time <sup>(2)</sup>		300	ns
t <sub>F</sub>	Inputs Fall Time <sup>(2)</sup>		300	ns
t <sub>SU.STO</sub>	Stop Set-up Time	0.6		μs
t <sub>DH</sub>	Data Out Hold Time	50		ns
t <sub>WR</sub>	Write Cycle Time		5	ms
Endurance <sup>(1)</sup>	5.0V, 25°C, Page Mode	1,000,000		Write Cycles

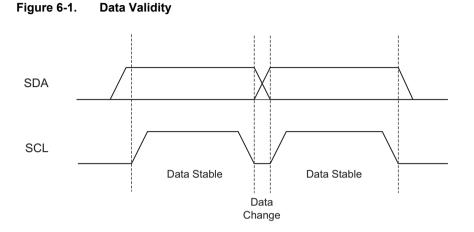
Notes: 1. This parameter is characterized and is not 100% tested ( $T_A = 25^{\circ}C$ ).

- 2. This parameter is characterized.
- 3. AC measurement conditions:
  - RL (connects to  $V_{CC}$ ): 1.3k $\Omega$  (2.5V, 5.5V), 10k $\Omega$  (1.7V)
  - Input pulse voltages:  $0.3V_{CC}$  to  $0.7V_{CC}$
  - Input rise and fall times:  $\leq$  50ns
  - Input and output timing reference voltages: 0.5 x V<sub>CC</sub>



### 6. Device Operation

**Clock and Data Transitions:** The SDA pin is normally pulled high with an external device. Data on the SDA pin may change only during SCL low time periods. Data changes during SCL high periods will indicate a Start or Stop condition as defined below.



**Start Condition:** A high-to-low transition of SDA with SCL high is a Start condition which must precede any other condition.

**Stop Condition:** A low-to-high transition of SDA with SCL high is a Stop condition. After a read sequence, the Stop condition will place the EEPROM in a standby power mode.

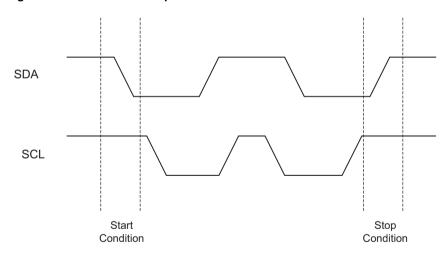
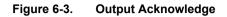
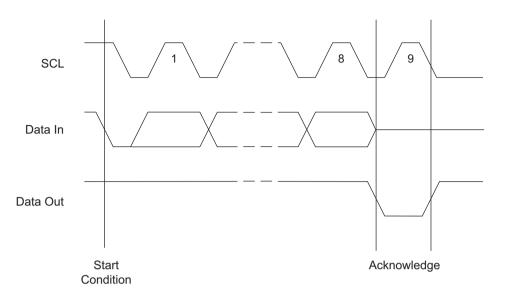


Figure 6-2. Start and Stop Definition



**Acknowledge:** All addresses and data words are serially transmitted to and from the EEPROM in 8-bit words. The EEPROM sends a zero to acknowledge that it has received each word. This happens during the ninth clock cycle.





Standby Mode: The AT24C128C/256C features a low-power standby mode which is enabled:

- Upon power-up.
- After the receipt of the stop bit and the completion of any internal operations.

Memory Reset: After an interruption in protocol, power loss, or system reset, any 2-wire part can be reset by following these steps:

- 1. Create a Start condition (if possible).
- 2. Clock nine cycles.
- 3. Create another Start condition followed by Stop condition as shown in the following figures.

The device should be ready for the next communication after above steps have been completed. In the event that the device is still non-responsive or remains active on the SDA bus, a power cycle must be used to reset the device

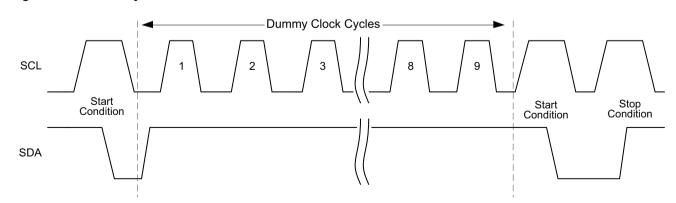
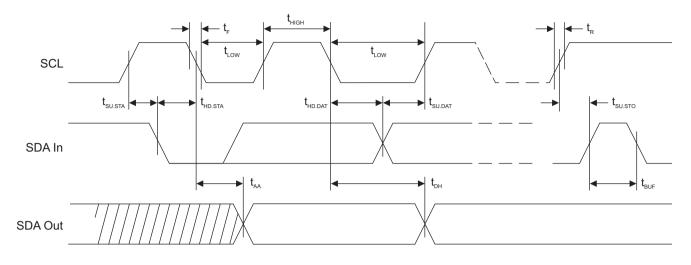


Figure 6-4. Memory Reset



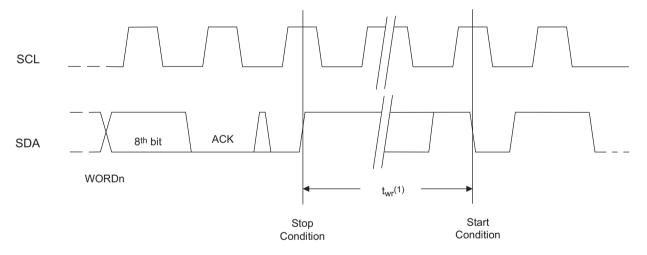
### Figure 6-5. Bus Timing



SCL: Serial Clock, SDA: Serial Data I/O

### Figure 6-6. Write Cycle Timing

SCL: Serial Clock, SDA: Serial Data I/O



Note: 1. The length of the self timed write cycle, or t<sub>WR</sub>, is defined as the amount of time from the Stop condition that begins the internal write operation, to the Start condition of the first Device Address byte sent to the device that it subsequently responds to with an ACK.



## 7. Device Addressing

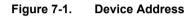
The 128K/256K EEPROM requires an 8-bit device address word following a start condition to enable the device for a read or write operation.

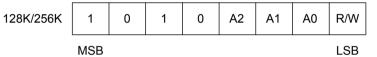
The device address word consists of a mandatory one, zero sequence for the first four most significant bits as shown. This is common to all the Serial EEPROM devices.

The 128K/256K uses the three device address bits,  $A_2$ ,  $A_1$ , and  $A_0$ , to allow as many as eight devices on the same bus. These bits must compare to their corresponding hardwired input pins. The  $A_2$ ,  $A_1$ , and  $A_0$  pins use an internal proprietary circuit that biases them to a logic low condition if the pins are allowed to float.

The eighth bit of the device address is the Read/Write operation select bit. A read operation is initiated if this bit is high and a write operation is initiated if this bit is low.

If the device address meets the requirements listed above, the device will acknowledge with a zero by pulling the SDA signal low. If the comparison is not made, the device will return to a standby state and the SDA signal will float high.

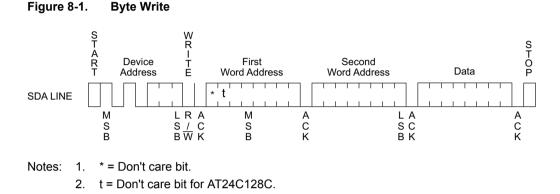






#### Write Operations 8.

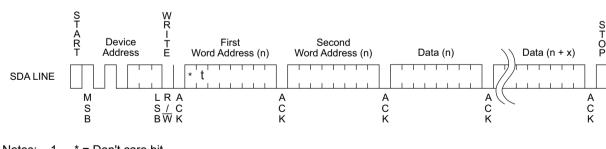
Byte Write: A write operation requires two 8-bit data word addresses following the device address word and acknowledgment. Upon receipt of this address, the EEPROM will again respond with a zero and then clock in the first 8-bit data word. Following receipt of the 8-bit data word, the EEPROM will output a zero and the addressing device, such as a microcontroller, must terminate the write sequence with a stop condition. At this time the EEPROM enters an internally timed write cycle, t<sub>WR</sub>, to the nonvolatile memory. All inputs are disabled during this Write Cycle and the EEPROM will not respond until the write is complete.



### Page Write: The 128K/256K EEPROM is capable of 64 byte page writes.

A Page Write is initiated the same as a Byte Write, but the microcontroller does not send a stop condition after the first data word is clocked in. Instead, after the EEPROM acknowledges receipt of the first data word, the microcontroller can transmit up to sixty-three more data words. The EEPROM will respond with a zero after each data word received. The microcontroller must terminate the Page Write sequence with a stop condition.

The data Word Address lower six bits are internally incremented following the receipt of each data word. The higher data Word Address bits are not incremented, retaining the memory page row location. When the Word Address, internally generated, reaches the page boundary, the following byte is placed at the beginning of the same page. If more than thirty-one data words are transmitted to the EEPROM, the data Word Address will roll-over and previous data will be overwritten.





Notes: 1. \* = Don't care bit.

> t = Don't care bit for AT24C128C. 2

Acknowledge Polling: Once the internally timed write cycle has started and the EEPROM inputs are disabled, Acknowledge Polling can be initiated. This involves sending a start condition followed by the device address word. The Read/Write bit is representative of the operation desired. Only if the internal write cycle has completed will the EEPROM respond with a zero, allowing the read or write sequence to continue.



## 9. Read Operations

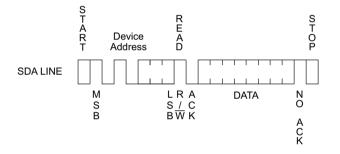
Read operations are initiated the same way as write operations with the exception that the Read/Write select bit in the device address word is set to one. There are three read operations:

- Current Address Read
- Random Address Read
- Sequential Read

**Current Address Read:** The internal data word address counter maintains the last address accessed during the last read or write operation, incremented by one. This address stays valid between operations as long as the device power is maintained. The address roll-over during read is from the last byte of the last memory page to the first byte of the first page. The address roll-over during write is from the last byte of the current page to the first byte of the same page.

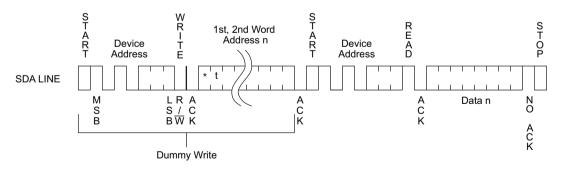
Once the device address with the Read/Write select bit set to one is clocked in and acknowledged by the EEPROM, the current address data word is serially clocked out. The microcontroller does not respond with an input zero but does generate a following Stop condition.

### Figure 9-1. Current Address Read



**Random Read:** A Random Read requires a dummy Byte Write sequence to load in the data Word Address. Once the device address word and data Word Address are clocked in and acknowledged by the EEPROM, the microcontroller must generate another start condition. The microcontroller now initiates a current address read by sending a device address with the Read/Write select bit high. The EEPROM acknowledges the device address and serially clocks out the data word. The microcontroller does not respond with a zero but does generate a following stop condition.



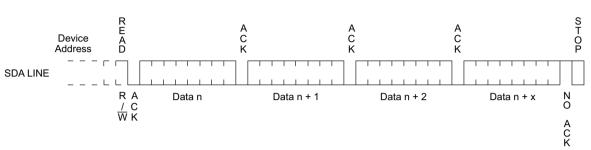


Notes: 1. \* = Don't care bit.

2. t = Don't care bit for AT24C128C.



**Sequential Read:** Sequential Reads are initiated by either a Current Address Read or a Random Address Read. After the microcontroller receives a data word, it responds with an acknowledge. As long as the EEPROM receives an acknowledge, it will continue to increment the data Word Address and serially clock out sequential data words. When the memory address limit is reached, the data Word Address will roll-over and the Sequential Read will continue. The Sequential Read operation is terminated when the microcontroller does not send an acknowledge (pull the SDA signal low), but does generate the Stop condition.



#### Figure 9-3. Sequential Read

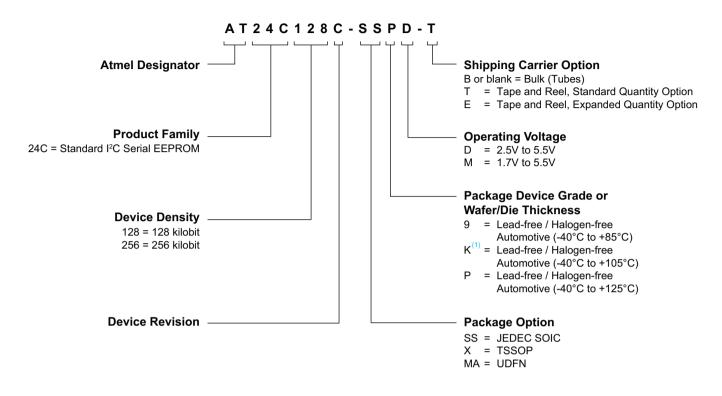
### 9.1 Power Recommendation

The device internal POR (Power-On Reset) threshold is just below the minimum operating voltage of the device. Power shall rise monotonically from 0.0Vdc to full  $V_{CC}$  in less than 1ms. Hold at full  $V_{CC}$  for at least 100µs before the first operation. Power shall drop from full  $V_{CC}$  to 0.0Vdc in less than 1ms. Power dropping to a non-zero level and then slowly going to zero is *not* recommended. Power shall remain off (0.0Vdc) for 0.5s minimum. Please consult Atmel if your power conditions do not meet the above recommendations.



## 10. Ordering Information

### 10.1 Ordering Code Details



Notes: 1. Contact Sales for Grade 2 Availability



## 10.2 Ordering Code Information

# 10.2.1 Automotive Grade 1, $V_{CC}$ = 2.5V to 5.5V

			Delivery Information			
Atmel Ordering Code	Lead Finish	Package	Form	Quantity	Operation Range	
AT24C128C-SSPD		8S1	Bulk (Tubes)	100 per Tube		
AT24C128C-SSPD-T	-	001	Tape and Reel	4,000 per Reel		
AT24C128C-XPD	NiPdAu	8X	Bulk (Tubes)	100 per Tube	Automotive Temperature	
AT24C128C-XPD-T	(Lead-free/Halogen-free)	0	Tape and Reel	5,000 per Reel	(-40°C to 125°C)	
AT24C128C-MAPD-T		8MA2	Tapa and Baal	5,000 per Reel		
AT24C128C-MAPD-E	-	8MA2	OIVIAZ	8MA2 Tape and Reel	15,000 per Reel	
AT2402500 0000				100 per Tube		
AT24C256C-SSPD	-	8S1	Bulk (Tubes)	100 per Tube		
AT24C256C-SSPD-T			Tape and Reel	4,000 per Reel		
AT24C256C-XPD	NiPdAu	8X	Bulk (Tubes)	100 per Tube	Automotive	
AT24C256C-XPD-T	(Lead-free/Halogen-free)	0	Tape and Reel	5,000 per Reel	Temperature (-40°C to 125°C)	
AT24C256C-MAPD-T			0.14.0	Tape and Reel	5,000 per Reel	
AT24C256C-MAPD-E		8MA2	Tape and Reel	15,000 per Reel		

Package Type					
8S1	8-lead, 0.150" wide, Plastic Gull Wing Small Outline (JEDEC SOIC)				
8X	8X 8-lead 4.4mm body, Plastic Thin Shrink Small Outline (TSSOP)				
8MA2	8MA2 8-pad, 2.00mm x 3.00mm body, 0.50mm pitch, Ultra Thin, Dual No Lead (UDFN)				



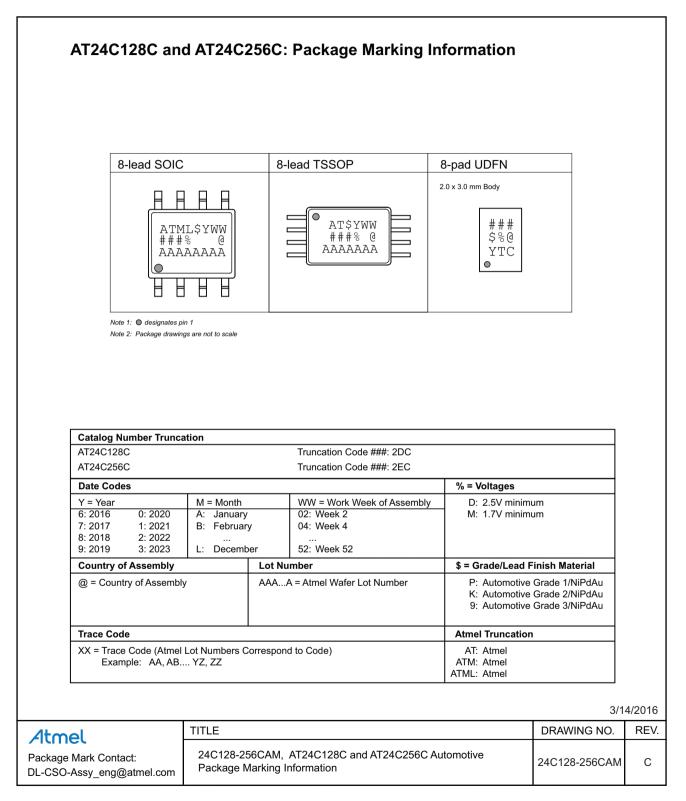
### 10.2.2 Automotive Grade 3, $V_{CC}$ = 1.7V to 5.5V

Atmel Ordering Code	Lead Finish	Package	Form	Quantity	Operation Range
AT24C128C-SS9M		8S1	Bulk (Tubes)	100 per Tube	
AT24C128C-SS9M-T	-	001	Tape and Reel	4,000 per Reel	
AT24C128C-X9M	NiPdAu	0.7	Bulk (Tubes)	100 per Tube	Automotive
AT24C128C-X9M-T	(Lead-free/Halogen-free)	8X	Tape and Reel	5,000 per Reel	Temperature (-40°C to 85°C)
AT24C128C-MA9M-T	-	8MA2	Tana and Daal	5,000 per Reel	
AT24C128C-MA9M-E	-	OIVIAZ	Tape and Reel	15,000 per Reel	
AT24C256C-SS9M		8S1	Bulk (Tubes)	100 per Tube	
AT24C256C-SS9M-T	-	001	Tape and Reel	4,000 per Reel	
AT24C256C-X9M	NiPdAu	8X	Bulk (Tubes)	100 per Tube	Automotive
AT24C256C-X9M-T	(Lead-free/Halogen-free)	ŏλ	Tape and Reel	5,000 per Reel	Temperature (-40°C to 85°C)
AT24C256C-MA9M-T		9144.2	Tana and Daal	5,000 per Reel	
AT24C256C-MA9M-E		8MA2	Tape and Reel	15,000 per Reel	

Package Type					
8S1	8-lead, 0.150" wide, Plastic Gull Wing Small Outline (JEDEC SOIC)				
8X	8-lead 4.4mm body, Plastic Thin Shrink Small Outline (TSSOP)				
8MA2	8-pad, 2.00mm x 3.00mm body, 0.50mm pitch, Ultra Thin, Dual No Lead (UDFN)				



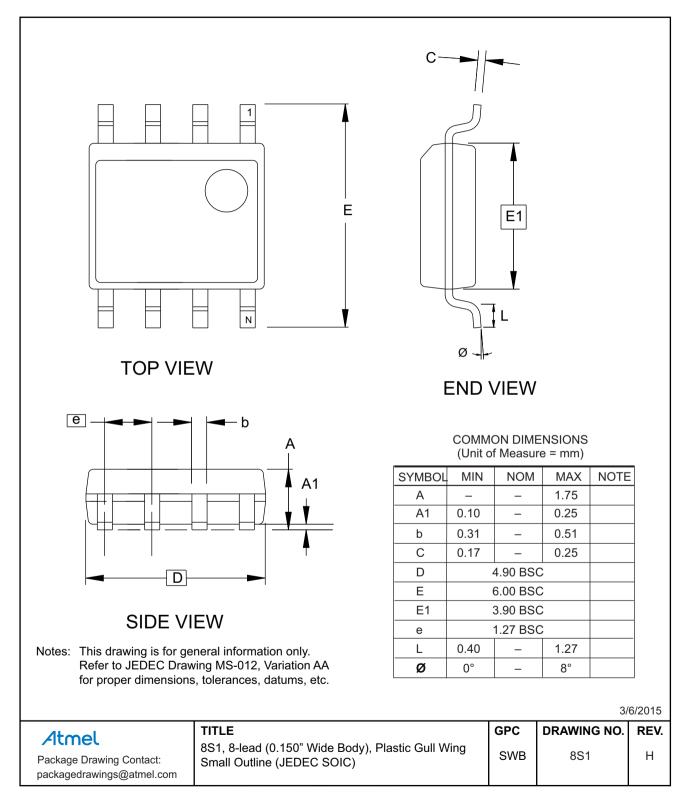
### 10.3 Product Markings





## 11. Packaging Information

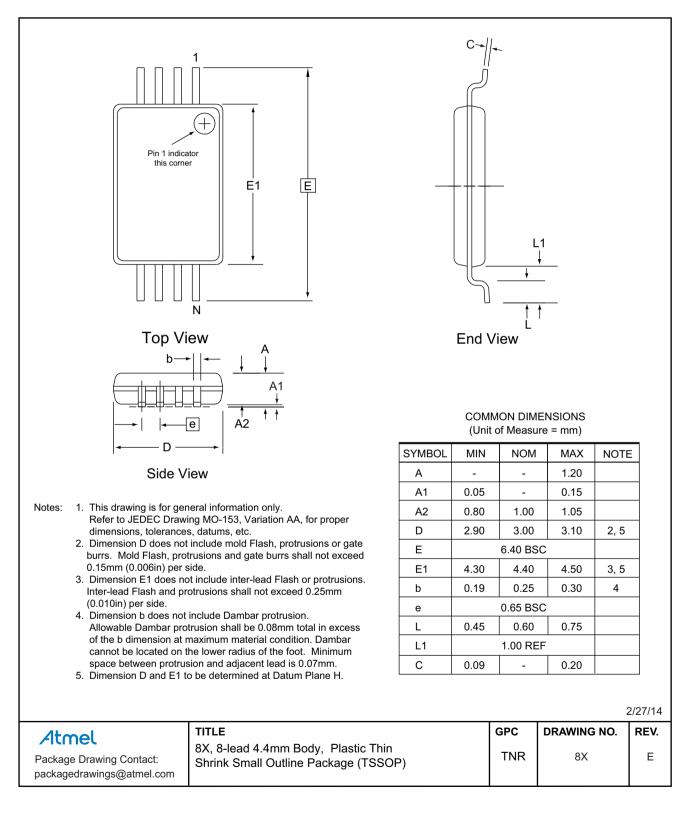
### 11.1 8S1 — 8-lead JEDEC SOIC



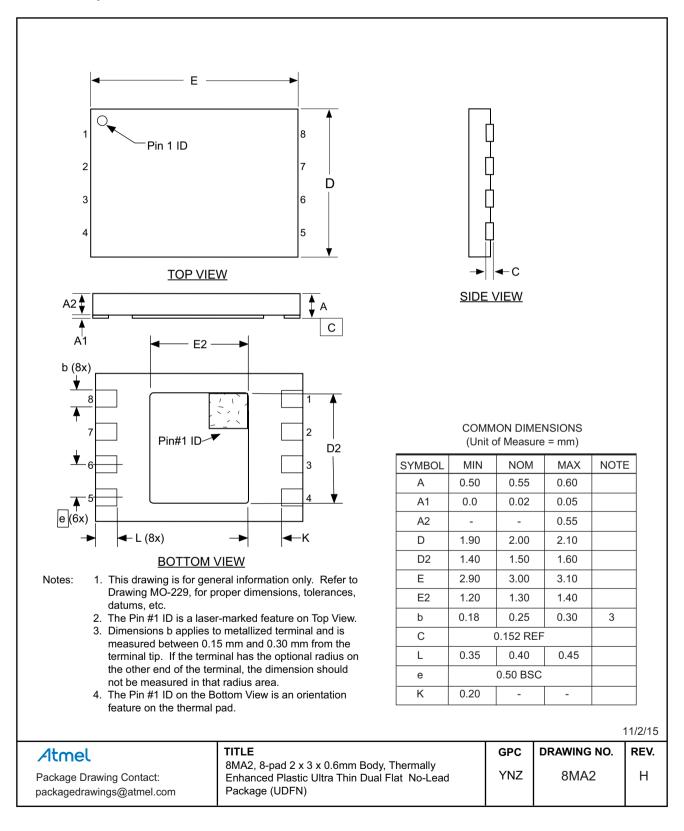


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### 11.2 8X — 8-lead TSSOP









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# 12. Revision History

Doc. Rev.	Date	Comments
8818C	07/2016	Added the Automotive Grade 2 and 3 and UDFN options and table of contents Updated the "Software Reset" section, part marking, 8S1 package drawing, disclaimer page, template and reorganize document.
8818B	10/2012	Removed preliminary status. Updated 8X — TSSOP package drawing and Atmel logos and disclaimer/copy page.
8818A	04/2012	Initial document release



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